



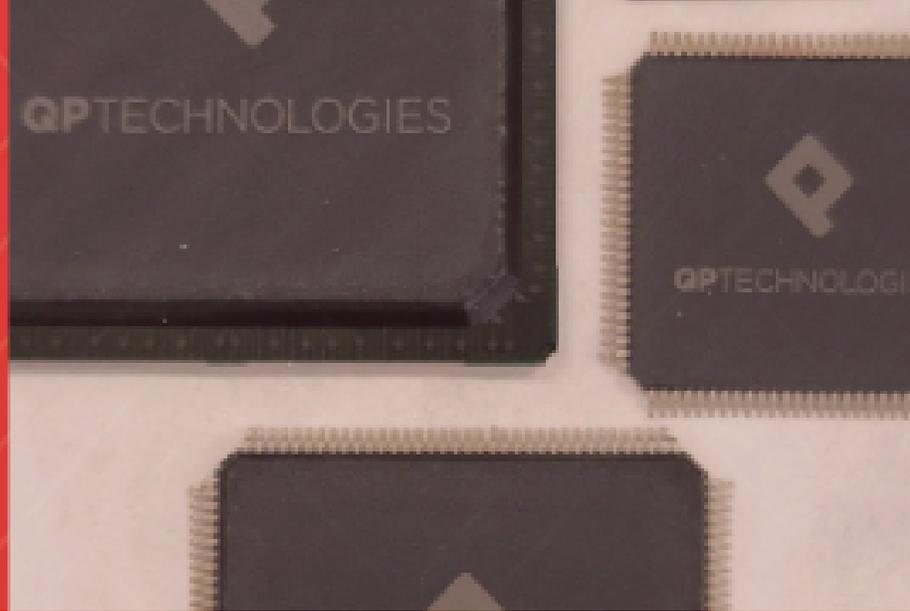
QPTECHNOLOGIES
MICROELECTRONIC PACKAGING & ASSEMBLY SOLUTIONS

December 2021 Newsletter

The holiday season is here! December is a busy month – not only because of the many holidays observed by different faiths, but also because, as the end of the calendar year approaches, we tend to be eager to “get things off our desks.” We want to complete as many projects as possible so that we can approach the new year with a clean slate and a fresh start. Never has that seemed more appealing, given what we have all been through these past two years. While the year ahead will surely hold new challenges, we look forward to 2022 with optimism and with gratitude for our families, for our QP Technology family, and for our extended family of customers, partners, influencers and vendors. We wish you peace, health and prosperity in the new year!

Our Holiday Schedule: Closed Friday, December 24 and Friday, December 31. Open for business Monday, December 27 – Thursday, December 30, 2021.

*Feature of the Month:
Leaded Plastic Packaging
(LPP)*



While QP Technologies works with the latest in package technologies, there remains demand for the mature package types in our line of leaded plastic packages (LPP). They are useful for small programs or companies with limited budgets that can use leaded versions of packages for new chips for prototyping, as well as for established products or systems for which leadless packages aren't required. We offer our trusted, reliable LPPs in a variety of sizes and types, enabling you to use them for a range of applications.

Our plastic package families include:

- SOP (small outline packages) in multiple formats, including small outline IC (SOIC), mini SOP (MSOP), quarter SOP (QSOP), shrink SOP (SSOP) and thin SSOP (TSSOP)
- PDIP (plastic dual inline packages)
- TQFP (thin quad flat packages)
- JEDEC-standard outlines

Our SOP and TQFP options are surface-mountable with gullwing lead formation for solid footing during assembly to a PCB, whether automated or using hand assembly. We can also quickly customize leadframes to meet your specific requirements, providing assembly services in our ITAR-registered stateside facility.

To learn more, please contact your local QP Technologies sales rep, or email sales@qptechnologies.com.

Employee Spotlight: Gabriela Till, Customer Service Representative

This month, we're highlighting one of our dynamic customer service team members. Gabriela (Gaby) Till joined QP Technologies in 2018 and serves as a highly valued interface between us and our customers, ensuring that your needs are met, and any issues are quickly addressed and resolved. Before signing on with QP Technologies, she held customer service positions with San Diego-area tech firms ATEC, Cartronics, and Vericom Global Solutions, as well as a variety of prior roles in buying/purchasing,



office management, and inside sales. Gaby truly embodies the phrase “customer satisfaction,” as she is 100% focused on helping strengthen your relationship and interactions with QP Technologies. Her personal belief is that by always maintaining a positive outlook, she can work with a customer to ensure good outcomes and resolutions to challenging situations. She is married and has a beloved cat named Remii (see photo). Gaby is happy to be part of the QP Technologies family, and the feeling is mutual!

Show Highlight: Promex to Sponsor iMAPS Advanced Packaging for Medical Microelectronics



Our parent company, Promex Industries, will be kicking off the new year here in San Diego, January 13-14, 2022, as an exhibitor and sponsor for iMAPS' 7th Advanced Technology Workshop on Advanced Packaging for Medical Microelectronics, at the Town & Country Hotel, Mission Valley.

The event will bring together technologists in semiconductor packaging with life science experts interested in applying advanced packaging methods to enable the next generation of medical microelectronic devices. Promex will showcase its concept-to-production assembly and fabrication capabilities for medical and biotech devices. These small component assemblies incorporate unique functionality as well as microelectronics, requiring complex fabrication processes. Examples of Class III devices that Promex can help fast-track include image sensors, diagnostic and disposable diagnostic devices, implantable devices, instruments and cameras, and wearable health devices.

For more information or to attend, please [click here](#).

About QP Technologies

QP Technologies is a leading provider of microelectronic packaging and assembly, wafer preparation, and substrate design and development services. We leverage proven technologies developed by our skilled staff, and we work closely with you to get your products to market quickly, with the highest quality prototype and production volumes.

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